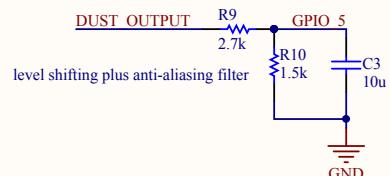
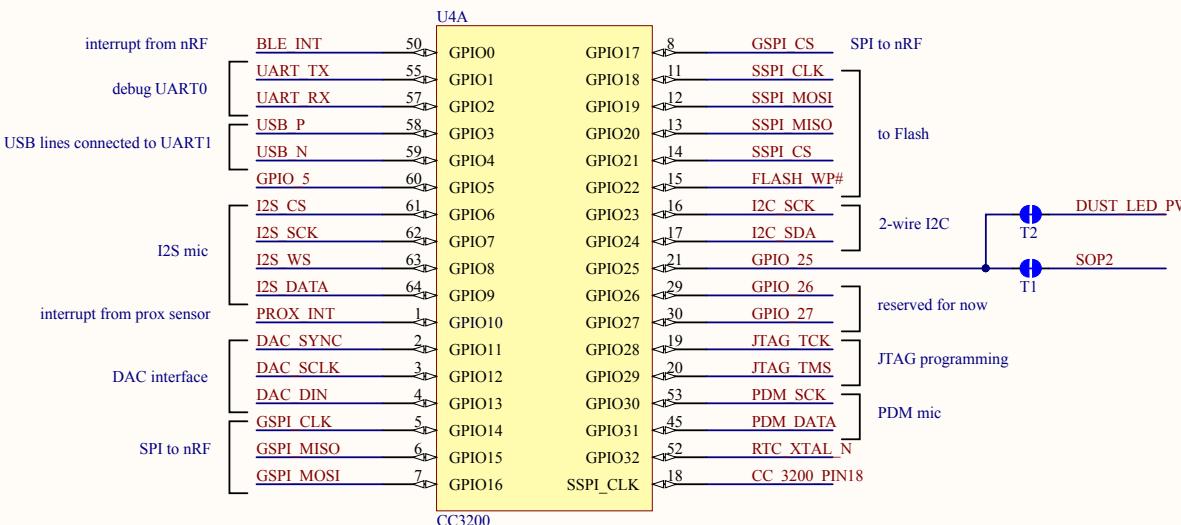
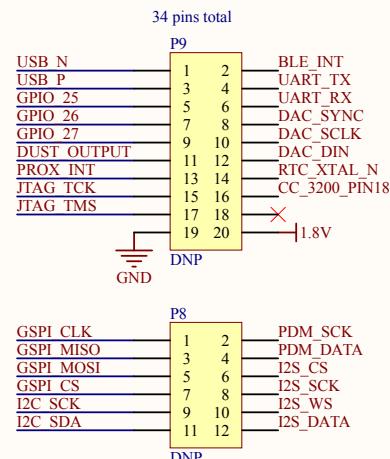


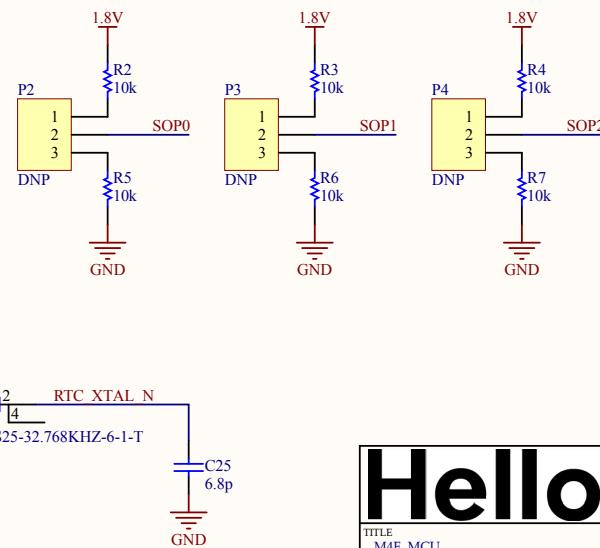
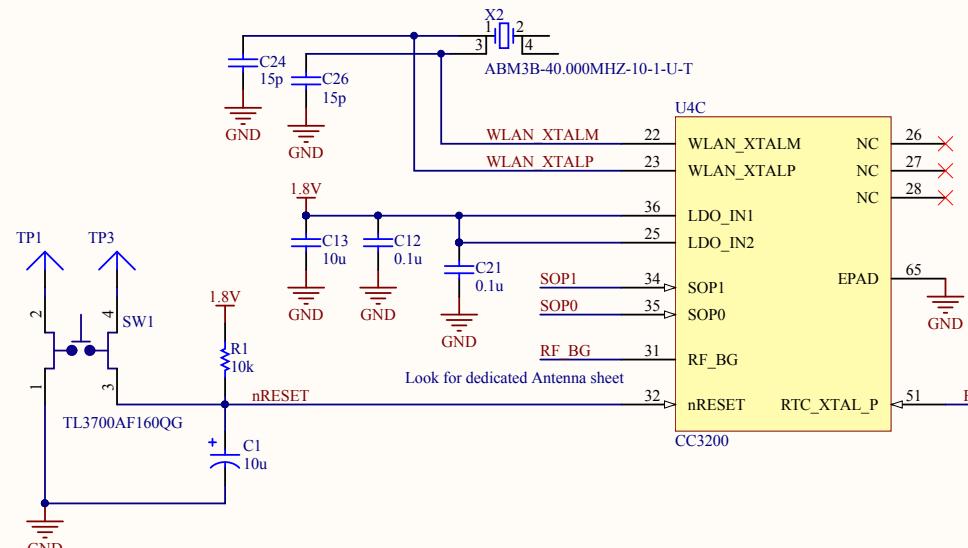
A



pin 52 can be used as GPIO when getting 32 kHz clk from another IC
pin 18 is not usable as GPIO

B

JTAG available to the developer via TMS and TCK pins
Defaults: P1 = 1-2, P2 = 2-3, P3 = 2-3



Hello

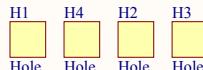
TITLE	REV
M4F MCU	1
6/4/2014	D. Fusi

A

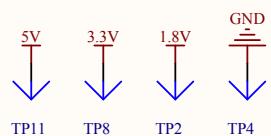
B

C

D

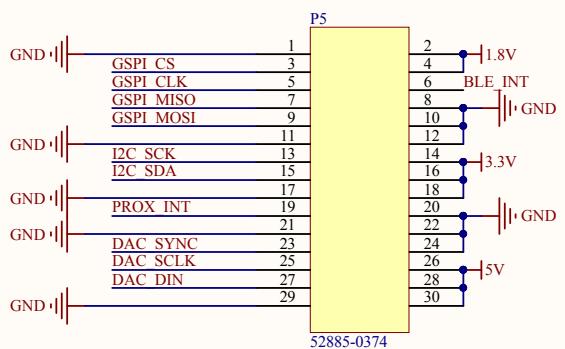


A

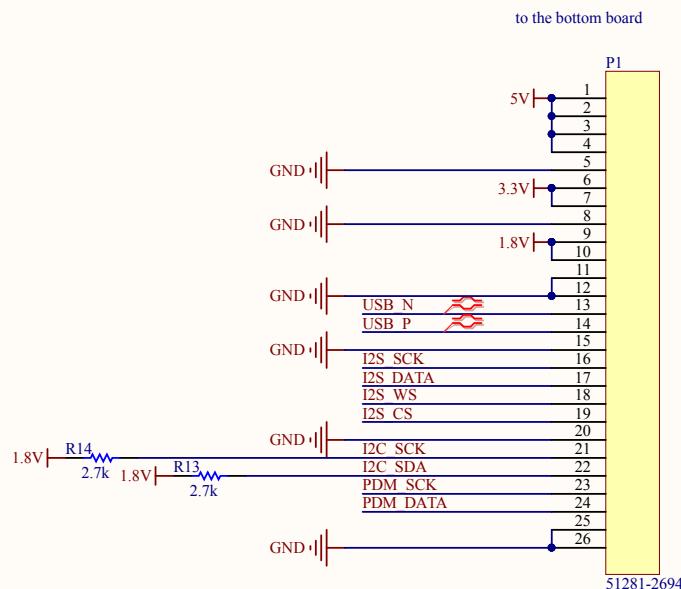


B

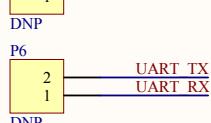
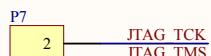
to the top board



C



programming / debugging connectors



Hello

TITLE	REV
Morpheus_middle	1
DATE	DRAWN BY
6/4/2014	D. Fusi

SHEET 2 OF 6

A

A

B

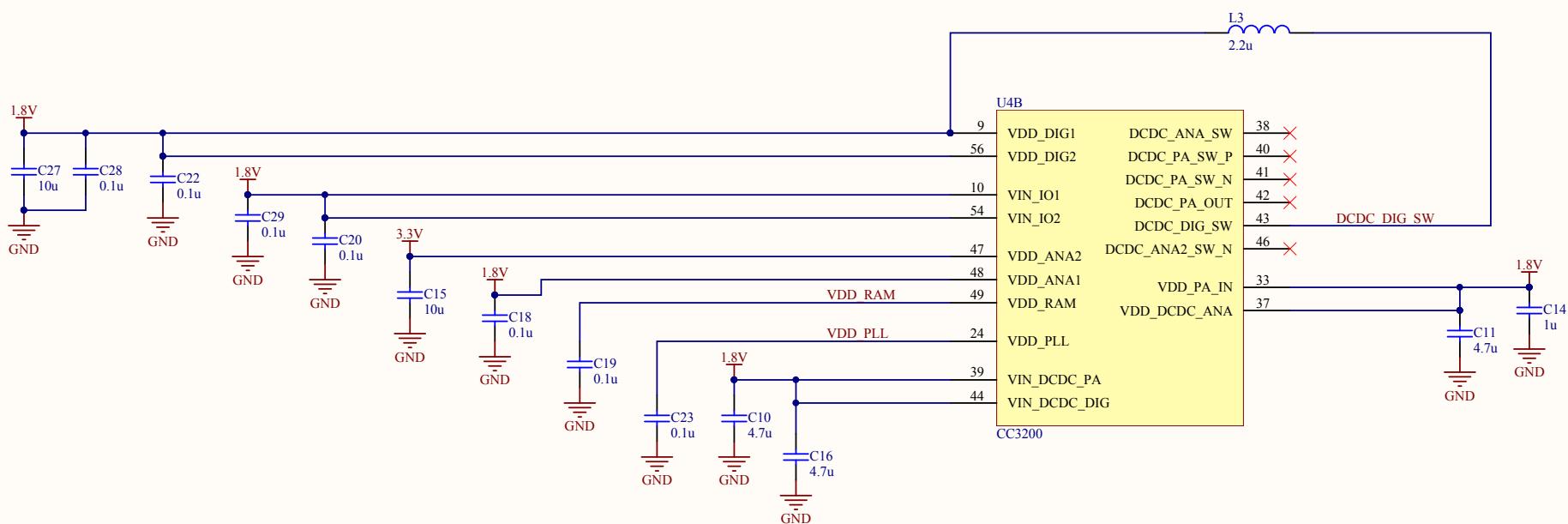
B

C

C

D

D



Hello

TITLE	REV
M4F MCU_Power	1
DATE	DRAWN BY
6/4/2014	D. Fusi

A

A

B

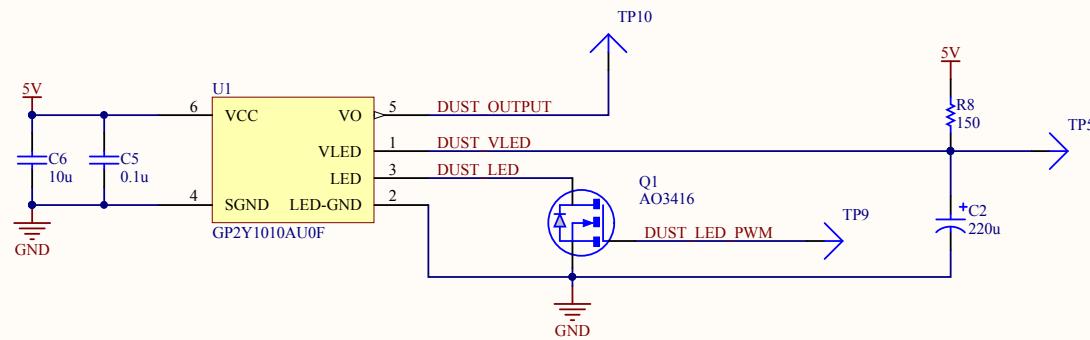
B

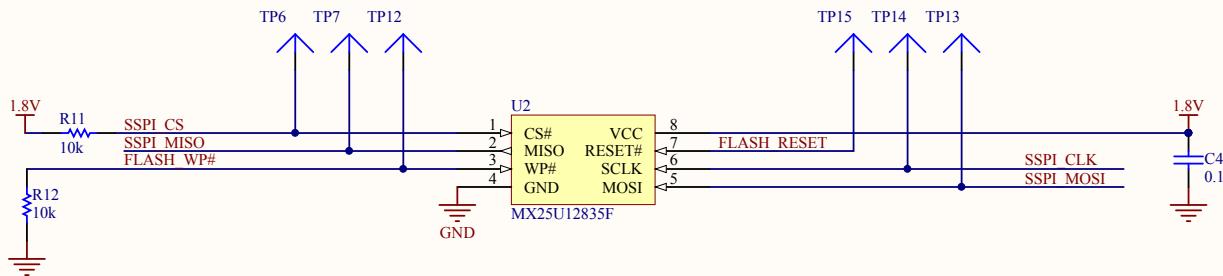
C

C

D

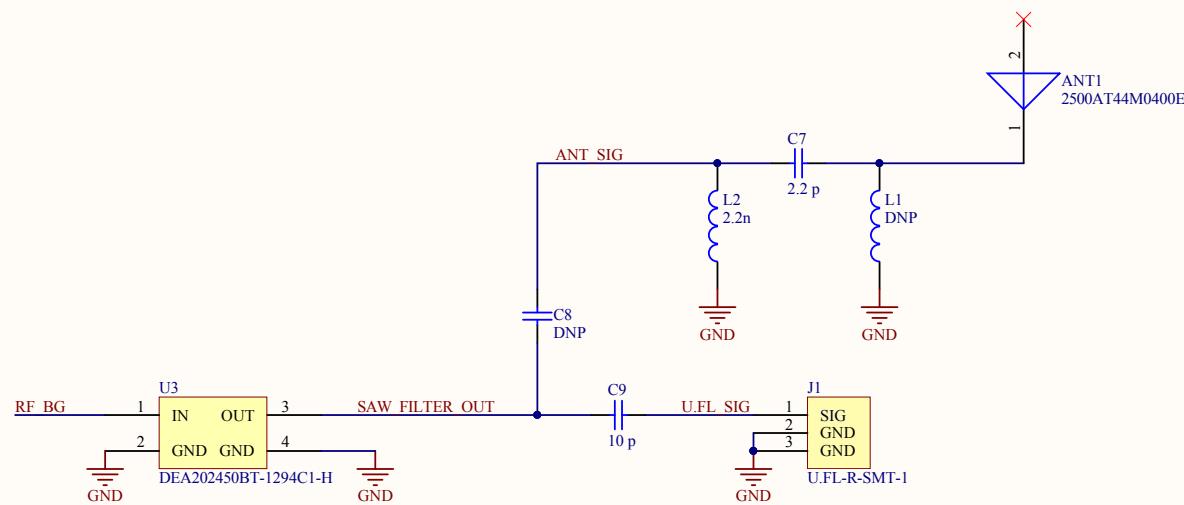
D



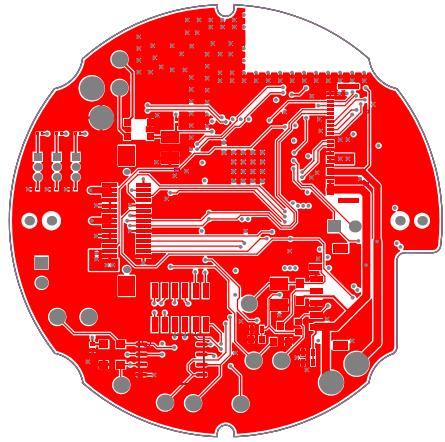


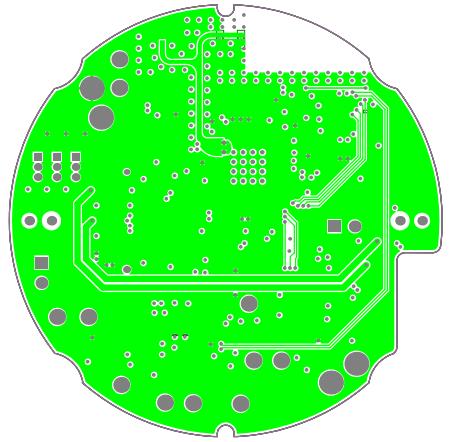
Hello

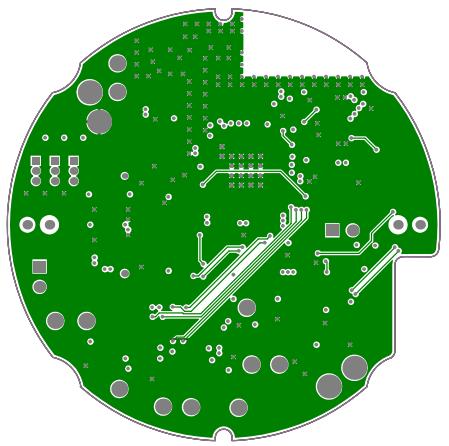
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DATE	6/4/2014	DRAWN BY
		SHEET 5 OF 6

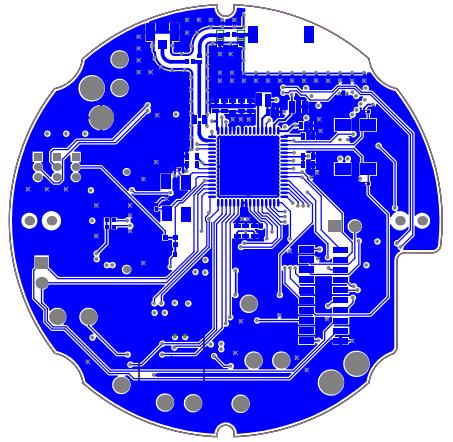


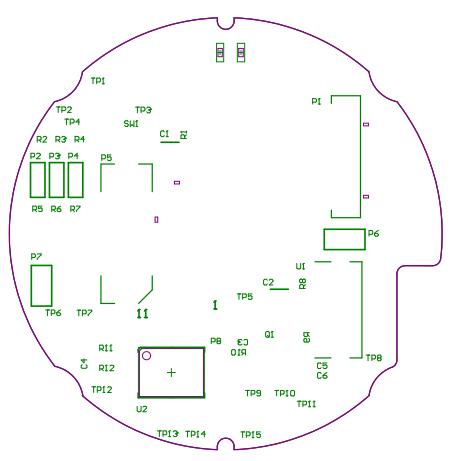
Hello	
TITLE M4F MCU_Antennas	REV 1
DATE 6/4/2014	DRAWN BY D. Fusi
SHEET 6 OF 6	

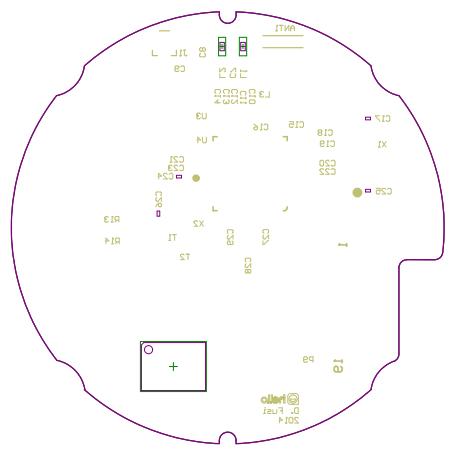


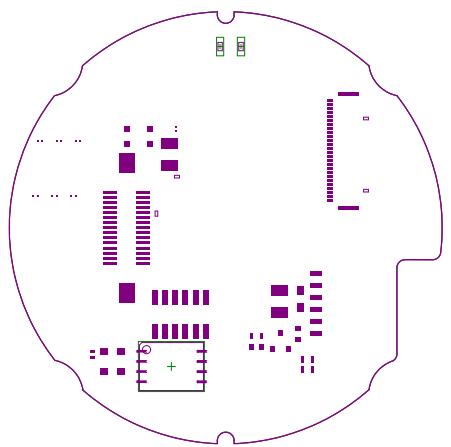


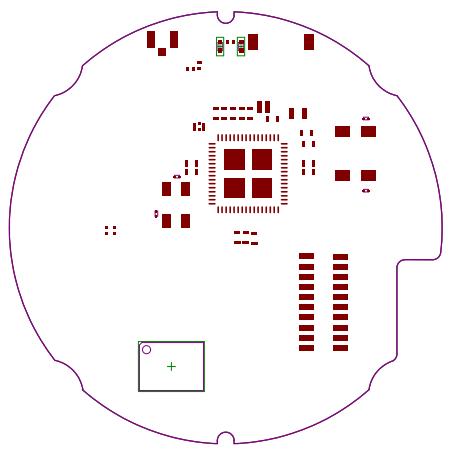


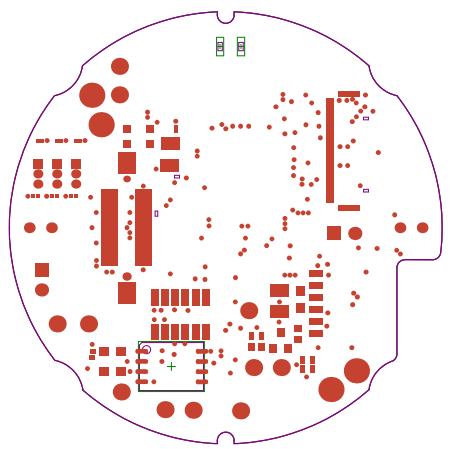


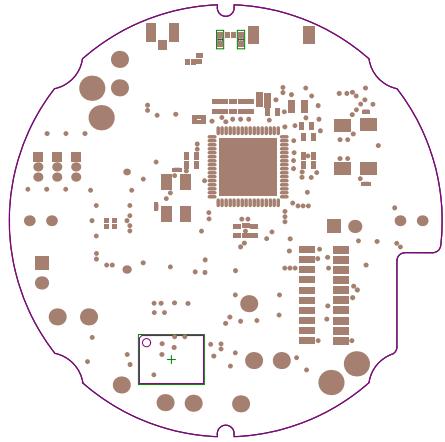


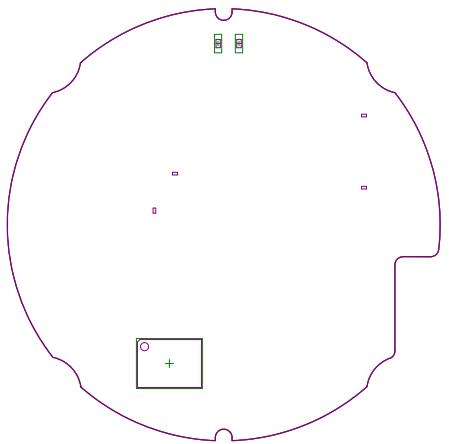


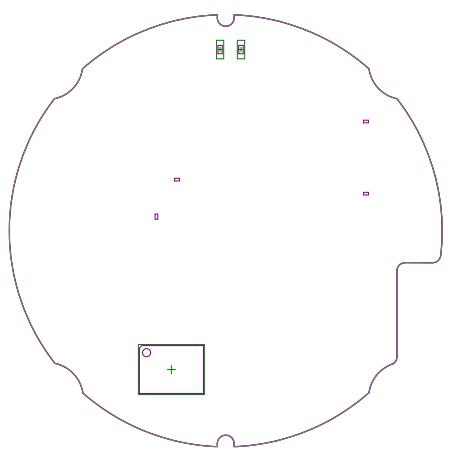


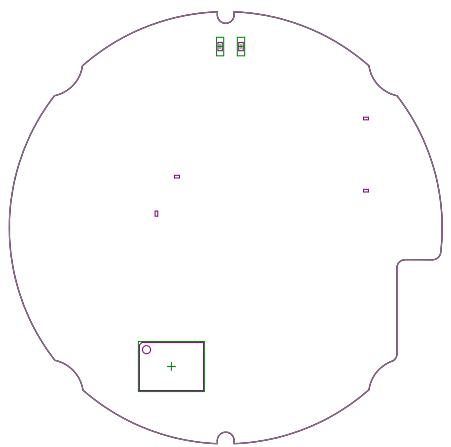


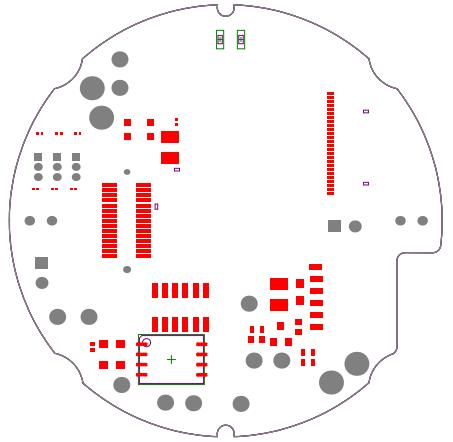


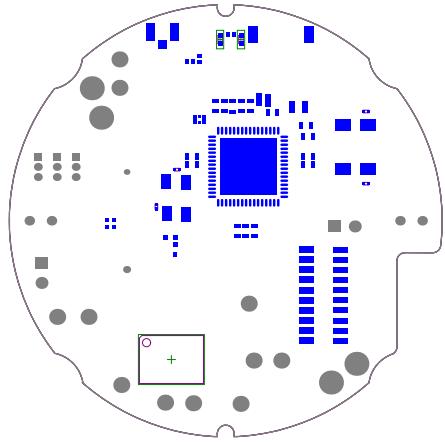


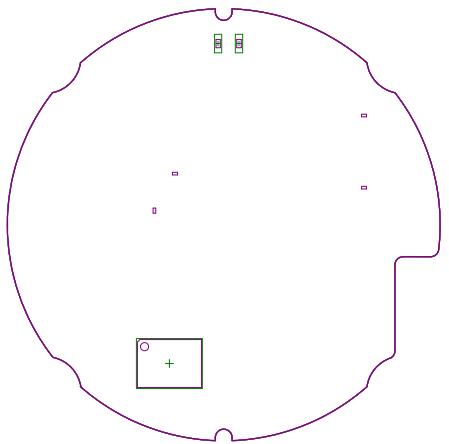












Fabrication / Assembly Notes

1. Material: Rigid
2. Number of electrical layers: 4
3. Trace / Space minimum: 5mil (all layers)
4. Thickness: 0.76mm (finished)
5. Finish: ENIG plating on exposed copper
6. Soldermask: per IPC-SM-840, color green registration within +/- 50um of circuit layer
7. Silkscreen: do print silkscreen on top and bottom layers
8. RoHS: parts shall be RoHS compliant as per European Union directive 2002/95/EC
9. Board must be lead free process compatible and able to withstand minimum of 5 cycles at 250 degrees celsius
10. All Test/QA/QC markings to be made on back side of PCB

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Paste				
2	Top Overlay				
3	Top Solder	Solder Resist	0.010mm	3.5	
4	Top Layer	Copper	0.036mm		
5	Dielectric 1	FR-4	0.254mm	4.2	
6	PWR	Copper	0.017mm		
7	Dielectric 2		0.254mm	4.2	
8	GND	Copper	0.017mm		
9	Dielectric 3		0.127mm	4.2	
10	Bottom Layer	Copper	0.036mm		
11	Bottom Solder	Solder Resist	0.010mm	3.5	
12	Bottom Overlay				
13	Bottom Paste				

Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
◊	1	0.700mm (27.56mil)	NPTH	Round
☒	1	0.900mm (35.43mil)	NPTH	Round
○	2	1.700mm (66.93mil)	NPTH	Round
☒	2	2.100mm (82.68mil)	NPTH	Round
◊	4	0.900mm (35.43mil)	PTH	Round
☒	4	2.400mm (94.49mil)	PTH	Round
□	9	0.600mm (23.62mil)	PTH	Round
▽	11	1.700mm (66.93mil)	PTH	Round
▼	18	0.300mm (11.81mil)	PTH	Round
■	229	0.200mm (7.87mil)	PTH	Round
	281 Total			

